

	Type	Hits	Search Text	DBs
1	BRS	6581	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$)	USPAT; JPO
2	BRS	4234	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate)	USPAT; JPO
3	BRS	873	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and solder adj (bump or ball)	USPAT; JPO
4	BRS	11	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and solder adj (bump or ball)	EPO; JPO
5	BRS	24	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and solder	EPO; JPO
6	BRS	0	6084297.pn.	EPO; JPO
7	BRS	1	6084297.pn.	USPAT; EPO; JPO
8	BRS	6	6084297.pn. or 5622590.pn. or 6069023.pn. or 6320257.pn. or 6251707.pn.	USPAT; EPO; JPO
9	BRS	3	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and buffer adj pad and wire	USPAT; JPO

	Type	Hits	Search Text	DBs
10	BRS	7	6084297.pn. or 5622590.pn. or 6069023.pn. or 6320257.pn. or 6251707.pn. or 6236568.pn.	USPAT; EPO; JPO
11	BRS	0	6294831.pn.	EPO; JPO
12	BRS	1	6294831.pn.	USPAT; EPO; JPO
13	BRS	0	6294831.pn. and (encapsulate or mold)	USPAT; EPO; JPO
14	BRS	0	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and ((QFN or "quad flat nonlead") adj lead adj frame) and solder adj (bump or ball)	USPAT; JPO
15	BRS	0	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and ((QFN or "quad flat nonlead") near (lead adj frame))	USPAT; JPO
16	BRS	0	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and ((QFN or "quad flat nonlead") near (lead adj frame))	USPAT; JPO
17	BRS	0	(chip or IC or die or semiconductor) and ((QFN or "quad flat nonlead") near (lead adj frame))	USPAT; JPO
18	BRS	0	((QFN or "quad flat nonlead") near (lead adj frame))	USPAT; JPO
19	BRS	12	((QFN or "quad flat nonlead") and (lead adj frame))	USPAT; JPO
20	BRS	12	((QFN or "quad flat nonlead") and (lead adj frame)) and (chip or IC or die or semiconductor)	USPAT; JPO

	Type	Hits	Search Text	DBs
21	BRS	6	((QFN or "quad flat nonlead") and (lead adj frame)) and (chip or IC or die or semiconductor) and heat	USPAT; JPO
22	BRS	3	6323065.pn. or 6306686.pn. or 5768774.pn.	USPAT; JPO
23	BRS	1359	257/\$.ccls. and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and wire	USPAT; JPO
24	BRS	2	(6169328.pn. or 6326700.pn.) and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and wire	USPAT; JPO
25	BRS	3	(6169328.pn. or 6326700.pn. or 6323065.pn.) and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and wire	USPAT; JPO
26	BRS	0	(6169328.pn. or 6326700.pn. or 6323065.pn.) and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and wire	JPO
27	BRS	75	heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and wire	JPO
28	BRS	12	6288900.pn. or 6236568.pn. or 6323065.pn. or 6127724.pn. or 6198171.pn. or 5622590.pn. or 6169328.pn. or 6326700.pn. or 6294831.pn. or 6084297.pn. or 6326687.pn. or 11284094.pn.	USPAT; JPO

	Type	Hits	Search Text	DBs
29	BRS	309	(257/675 or 257/720 or 257/778) and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and solder adj (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
30	BRS	193	(257/787 or 257/788 or 257/796) and heat adj (sink or spreader or transfer or dissipation) and (chip or IC or die or semiconductor) and (mold or encapsul\$) and (carrier or substrate) and solder adj (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB